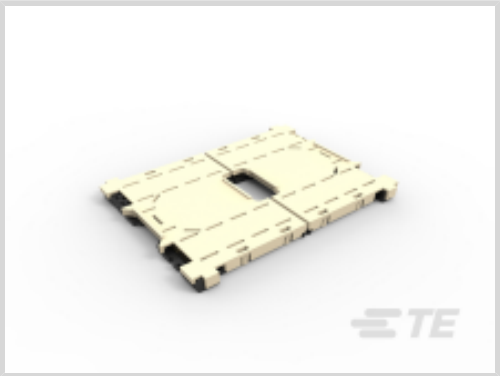




Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 Sockets



IC Socket Type: **LGA 3647**

Number of Positions: **3647**

Contact Mating Area Plating Material Thickness: **[ 30 µin ]**

Centerline (Pitch): **.86 mm, .99 mm [ .039 in, .034 in ]**

Termination Method to PCB: **Surface Mount - Solder Ball**

[All LGA 3647 Sockets \(0\)](#)

Features

Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

Body Features

Frame Style	Square
-------------	--------

Packaging Features

Packaging Method	Tray
------------------	------

Operation/Application

Circuit Application	Signal
---------------------	--------

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board

Housing Features

Housing Color	Black
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	.86 mm, .99 mm[.039 in][.034 in]

Contact Features

Contact Mating Area Plating Material	Gold
--------------------------------------	------



Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
	30 µin
Contact Current Rating (Max)	.5 A

Configuration Features

Number of Positions	3647
Grid Spacing	.9906 x .8585 mm[.039 x .0338 in]

Termination Features

Termination Method to PCB	Surface Mount - Solder Ball
---------------------------	-----------------------------

Mechanical Attachment

Connector Mounting Type	Board Mount
-------------------------	-------------

Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C


Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits




as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>


Compatible Parts




TE Part # 2821719-3  
IFP/LEC CBL ASSY 2 PORT TYPE A STR




TE Part # 2821720-1  
IFP/LEC CBL ASSY 2 PORT TYPE A STR INV




TE Part # 2821719-1  
IFP/LEC CBL ASSY 2 PORT TYPE A STR



TE Part # 2821720-2  
IFP/LEC CBL ASSY 2 PORT TYPE A STR INV



TE Part # 2821719-4  
IFP/LEC CBL ASSY 2 PORT TYPE A STR



TE Part # 2821719-2  
IFP/LEC CBL ASSY 2 PORT TYPE A STR

Customers Also Bought



TE Part #CAT-103156-WBHSM  
Receptacle Housing: Wire-to-Board, with Mating Alignment, SL156



TE Part #641550-1  
SL156 RECPT PTPBR



TE Part #2-2822979-3  
LGA3647-0 SOCKET P0 KIT FOR ODM (30U AU)

Documents

Product Drawings  
LGA3647-1 SOCKET-P1 KIT FOR ODM (30U AU)

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_2-2822979-4\_C.2d\_dxf.zip

English

Customer View Model



[ENG\\_CVM\\_CVM\\_2-2822979-4\\_C.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2-2822979-4\\_C.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[LGA 3647 Socket Product Flyer](#)

English

Product Specifications

[Application Specification](#)

English